12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20230711003.1A
Qualification of RFAB as an additional Fab site option for select HPA07 devices
Change Notification / Sample Request

Date: August 09, 2023
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

Revision A is to announce the addition of new devices that were not included in the original PCN notification.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20230711003.1A
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DAC8811IBDGKR	null
DAC8811IBDGKT	null
DAC8811IBDRBT	null
DAC8811ICDGKT	null
DAC8801IDGKR	null
DAC8801IDGKT	null
DAC8811ICDRBT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20230711003.1A	**PCN Date:**	August 09, 2023
Title:	Qualification of RFAB as an additional Fab site option for select HPA07 devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	Oct 11, 2023	**Sample requests accepted until:**	August 11, 2023*

***Sample requests received after August 11, 2023 will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Revision A is to announce the addition of nine new devices that were not included in the original PCN notification. The new devices are highlighted in yellow and **bolded** in the product affected section below. For these newly added devices ONLY, the expected first shipment date for the new devices will be 90 days from the date of this notice, and sample requests will be accepted until 30 days from the date of this notice. The proposed 1st ship date of October 11, 2023 still applies for the original set of devices.

Texas Instruments is pleased to announce the addition of RFAB as an additional Wafer Fab site option for the products listed in the "Product Affected" section of this document.

Current Fab Site			New Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**New Fab Site**	**Process**	**Wafer Diameter**
DP1DM5	HPA07	200mm	RFAB	HPA07	300mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

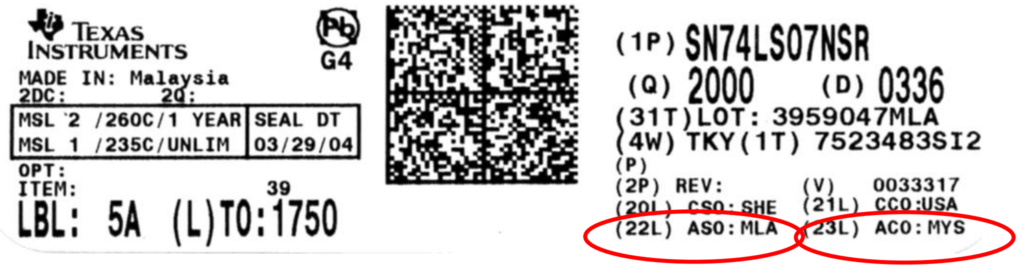
None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas
RFAB	**RFB**	**USA**	**Richardson**

Sample product shipping label (not actual product label)



TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750

G4

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

ADS1191IPBS	ADS1192IRSMT	ADS1292IRSMR	**DAC8811IBDRBT**
ADS1191IPBSR	ADS1291IPBS	ADS1292IRSMT	**DAC8811ICDGKR**
ADS1191IRSMR	ADS1291IPBSR	**DAC8801IDGKR**	**DAC8811ICDGKT**
ADS1191IRSMT	ADS1291IRSMR	**DAC8801IDGKT**	**DAC8811ICDRBT**
ADS1192IPBS	ADS1291IRSMT	**DAC8801IDRBT**	
ADS1192IPBSR	ADS1292IPBS	**DAC8811IBDGKR**	
ADS1192IRSMR	ADS1292IPBSR	**DAC8811IBDGKT**	

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: ADS1292IRSMR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: AMC7836IPAP	QBS Process Reference: INA231AIYFDR	QBS Process Reference: INA231BIYFDR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	3/231/0	3/231/0	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	3/231/0	-	1/77/0	2/154/0
HTOL	B1	Life Test	140C	480 Hours	-	1/77/0	2/154/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	1/77/0	1/77/0	2/154/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	1/1000/0	2/2000/0	-	1/1000/0	2/2000/0
ESD	E2	ESD CDM	-	200 Volts	-	3/9/0	3/9/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	1/3/0	-	2/6/0

Type	#	Test Name	Condition	Duration	Qual Device: ADS1292IRSMR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: AMC7836IPAP	QBS Process Reference: INA231AIYFDR	QBS Process Reference: INA231BIYFDR
ESD	E2	ESD CDM	-	350 Volts	-	-	-	-	1/3/0	-
ESD	E2	ESD CDM	-	500 Volts	1/3/0	-	-	-		-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	3/9/0	3/9/0	1/3/0	1/3/0	2/6/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	3/9/0	3/9/0	1/3/0	1/6/0	2/12/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	2/60/0
FTY	E6	Final Test Yield	-	-	1/Pass	-	-	-	-	-

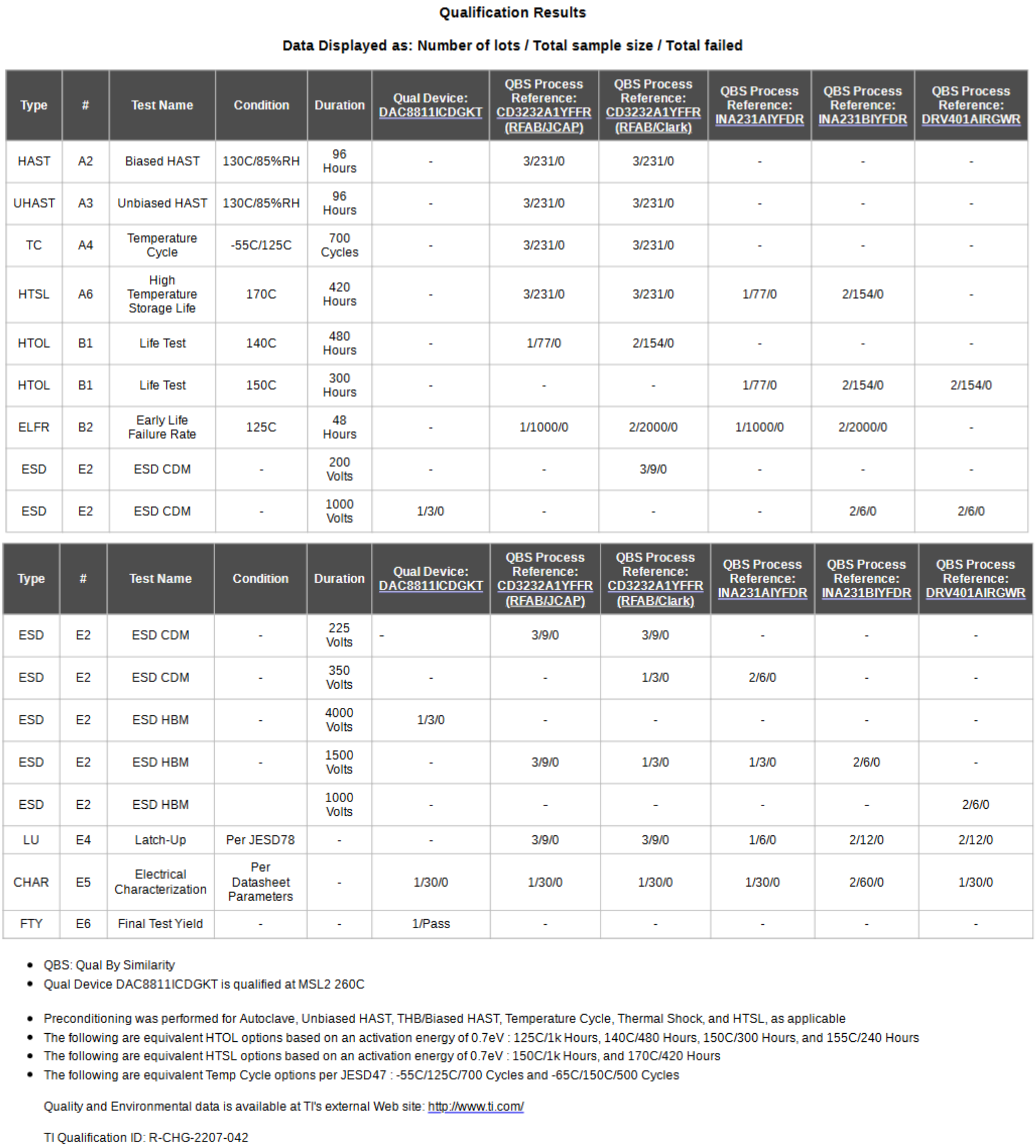
- QBS: Qual By Similarity
- Qual Device ADS1292IRSMR is qualified at MSL2 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2208-068

PCN Rev A Qual Memo



Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: DAC8811ICDGKT	QBS Process Reference: CD3232A1YFFR (RFAB/JCAP)	QBS Process Reference: CD3232A1YFFR (RFAB/Clark)	QBS Process Reference: INA231AIYFDR	QBS Process Reference: INA231BIYFDR	QBS Process Reference: DRV401AIRGWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	3/231/0	3/231/0	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	3/231/0	1/77/0	2/154/0	-
HTOL	B1	Life Test	140C	480 Hours	-	1/77/0	2/154/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	1/77/0	2/154/0	2/154/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	1/1000/0	2/2000/0	1/1000/0	2/2000/0	-
ESD	E2	ESD CDM	-	200 Volts	-	-	3/9/0	-	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-	2/6/0	2/6/0
ESD	E2	ESD CDM	-	225 Volts	-	3/9/0	3/9/0	-	-	-
ESD	E2	ESD CDM	-	350 Volts	-	-	1/3/0	2/6/0	-	-
ESD	E2	ESD HBM	-	4000 Volts	1/3/0	-	-	-	-	-
ESD	E2	ESD HBM	-	1500 Volts	-	3/9/0	1/3/0	1/3/0	2/6/0	-
ESD	E2	ESD HBM		1000 Volts	-	-	-	-	-	2/6/0
LU	E4	Latch-Up	Per JESD78	-	-	3/9/0	3/9/0	1/6/0	2/12/0	2/12/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	2/60/0	1/30/0
FTY	E6	Final Test Yield	-	-	1/Pass	-	-	-	-	-

- QBS: Qual By Similarity
- Qual Device DAC8811ICDGKT is qualified at MSL2 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2207-042

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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